

T-35-25-

TOPAZ
SEMICONDUCTOR

SD217, SD219

**N-CHANNEL ENHANCEMENT-MODE
D-MOS POWER FET**

ORDERING INFORMATION

TO-206AF (TO-72) Package	SD217DE	SD219DE
Shorting Ring	SD217DE/R	SD219DE/R
Sorted Chips in Waffle Pack	SD217CHP	SD219CHP
Description	6.0 ohm, 25V V _{SB} = 15V min	6.0 ohm, 25V V _{SB} = 20V min

FEATURES

- CMOS Compatible Input
- Small Package, Standard Pin-Out
- TTL and CMOS Compatible Input
- Low Capacitance
- Peak Pulsed Current, 1 Amp min

APPLICATIONS

- ± 10V Analog Switch, SD219DE
- ± 7.5 Analog Switch, SD217DE
- High Speed, Medium Power, Switch Drivers
- Sample and Hold and Track and Hold
- A-to-D and D-to-A Converters

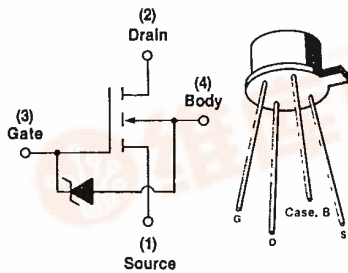
ABSOLUTE MAXIMUM RATINGS (T_A = +25°C unless otherwise specified)

V _{DS} Drain-Source Voltage	+25V
V _{DB} Drain-Body Voltage	+22.5V
SD217	+22.5V
SD219	+25V
V _{SD} Source-Drain Voltage	+15V
SD217	+15V
SD219	+20V
V _{SB} Source-Body Voltage	+22.5V
SD217	+22.5V
SD219	+25V
V _{GB} Gate-Body Voltage	+30V
V _{GS} Gate-Source Voltage	±22.5V
V _{GD} Gate-Drain Voltage	±22.5V
I _D Peak Pulsed Drain Current	+1.0A

I _D Continuous Drain Current (Note 1)	160mA
P _D Continuous Power Dissipation (Note 1)	
T _A = +25°C (Free Air)	300mW
T _C = +25°C (Infinite Heat Sink)	1.2W
Power Derating Factors (Note 1)	
Free Air	3.0mW/°C
Infinite Heat Sink	12mW/°C
Thermal Resistance (Note 1)	
θ _{JA} Junction to Ambient	333°C/W
θ _{JC} Junction to Case	83°C/W
T _{op} Operating Junction Temperature Range	-55 to +125°C
T _{stg} Storage Temperature Range	-55 to +150°C

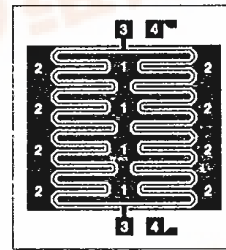
Note 1: Not applicable to chips. Final value depends on mounting.

SCHEMATIC DIAGRAM



PACKAGE DIMENSIONS (TO-72) TO-206AF
(See Package 3)

CHIP CONFIGURATION



1—Drain 2—Source 3—Gate 4—Diode
Minimum bonding required. One Drain, One Source (left), One Source (right), One Gate. Bond Gate and Adjacent Diode to Common Point to Connect Protective Diode.
Size: .040 x .044 x .013 inch.
Body (Substrate) is backside contact.





SD217, SD219

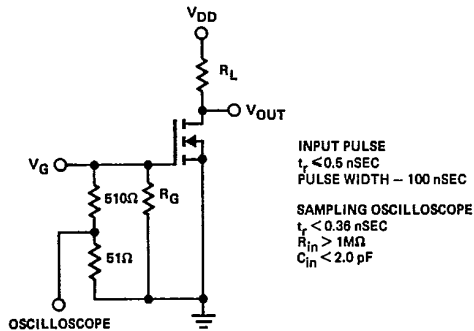
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ELECTRICAL CHARACTERISTICS (T_A = +25°C unless otherwise specified)

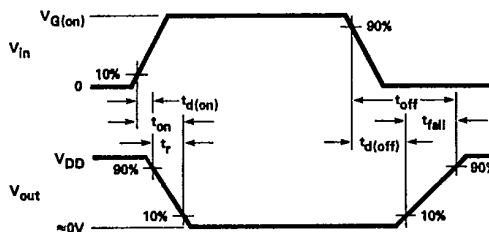
#	CHARACTERISTIC		MIN	TYP	MAX	UNITS	TEST CONDITIONS
1	BV _{DS}	Drain-Source Breakdown Voltage	25	30		V	I _D = 10μA, V _{GS} = V _{BS} = 0
2			15	20			I _D = 100nA, V _{GS} = V _{BS} = -5V
3	BV _{SD}	Source-Drain Breakdown Voltage	SD217 15			V	I _S = 100nA, V _{GD} = V _{BD} = -5V
4			SD219 20				
5	BV _{DB}	Drain-Body Breakdown Voltage	SD217 22.5			V	I _D = 100nA, V _{GB} = 0, Source Open
6			SD219 25				
7	BV _{SB}	Source-Body Breakdown Voltage	SD217 22.5			V	I _S = 100nA, V _{GB} = 0, Drain Open
8			SD219 25				
9	I _{D(off)}	Drain-Source OFF Leakage Current			100	nA	V _{DS} = 15V, V _{GS} = V _{BS} = -5V
10	I _{S(off)}	Source-Drain OFF Leakage Current			100		V _{SD} = 15V, V _{GD} = V _{BD} = -5V
11	I _{GB}	Gate-Body ON Leakage Current			10	μA	V _{GB} = 30V, V _{GS} = V _{GD} = 22.5V
12	V _{GS(th)}	Gate-Source Threshold Voltage	0.1		2.0	V	V _{DS} = V _{GS} , I _D = 10μA, V _{SB} = 0
13	I _{D(on)}	Drain-Source ON Current (Note 1)	1.0			A	V _{DS} = V _{GS} = 10V, V _{SB} = 0
14	r _{DS(on)}	Drain-Source ON Resistance (Note 1)			8.0	ohms	V _{GS} = 5.0V
15					6.0		I _D = 50mA V _{SB} = 0
16					6.0		V _{GS} = 10V I _D = 500mA V _{SB} = 0
17	g _{fs}	Common-Source (Note 1) Forward Transconductance	100			mmhos	V _{DS} = 15V, I _D = 200mA V _{SB} = 0, F = 1KHz
18	C _(gs + gd + gb)	Gate Node Capacitance			30	pF	V _{DS} = 10V, V _{GS} = V _{BS} = -15V f = 1MHz
19	C _(gd + db)	Drain-Node Capacitance			15		
20	C _(gs + sb)	Source Node Capacitance			40		
21	C _(dg)	Reverse Transfer Capacitance			5.0		
22	t _{on}	Turn ON Time		2.0	4.0	nS	V _{DD} = 10V, V _{G(on)} = 10V R _L = 133Ω, R _G = 51Ω
23	t _{off}	Turn OFF Time		3.0	5.0		

Note 1: Pulse Test 80μSec, 1% Duty Cycle

SWITCHING TIMES TEST CIRCUIT



TEST WAVEFORMS

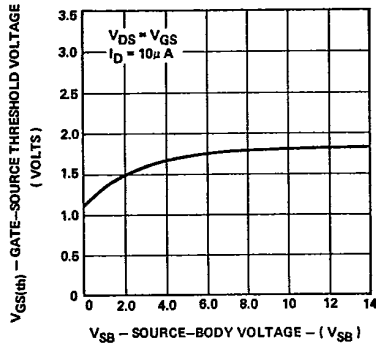




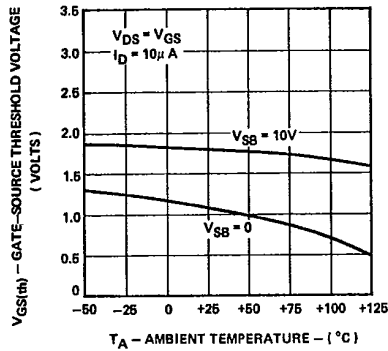
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TYPICAL PERFORMANCE CHARACTERISTICS ($T_A = +25^\circ\text{C}$ unless otherwise specified)

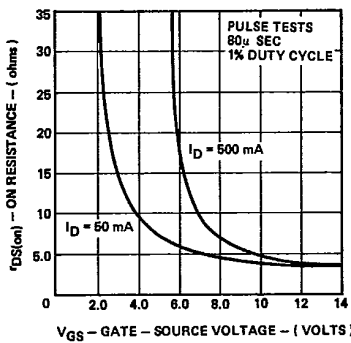
GATE-SOURCE THRESHOLD VOLTAGE
—VS—
SOURCE-BODY VOLTAGE



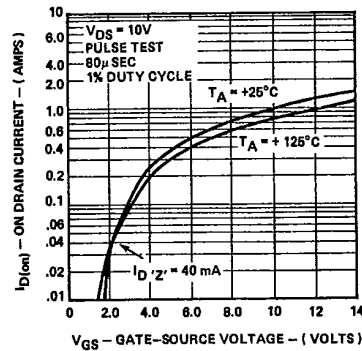
GATE-SOURCE THRESHOLD VOLTAGE
—VS—
TEMPERATURE



DRAIN-SOURCE ON RESISTANCE
—VS—
GATE-SOURCE VOLTAGE



ON DRAIN CURRENT
—VS—
GATE-SOURCE VOLTAGE



FORWARD TRANSCONDUCTANCE
—VS—
ON DRAIN CURRENT

